Product/Process Change Notice - PCN 19_0162 Rev. -

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. Any inquiries or requests with this PCN (additional data or samples) must be sent to ADI within 30 days of publication date. ADI contact information is listed below.

PCN Title:	Notification of ADI Penang as an Alternate Assembly Site and Mold Compound Change for LTM8002		
Publication Date:	07-Aug-2019		
Effectivity Date:	09-Nov-2019 (the earliest date that a customer could expect to receive changed material)		
Revision Description:			

Initial Release

Description Of Change:

ADI is adding ADI Penang site as an alternate assembly facility for LTM8002. In addition, new mold compound has been qualified in LTM8002 which is the next generation mold compound going forward. The new mold compound uses fine filler and facilitates the filling of tighter spaces.

Reason For Change:

To add ADI Penang as an alternate assembly site to ensure continuous availability of a reliable source of product supply. To standardize epoxy mold compound at all assembly locations using Sumitomo G311E for LTM8002.

Impact of the change (positive or negative) on fit, form, function & reliability:

The change is transparent in customer applications since there is no change in form, fit, function, quality or reliability of the products. The product datasheet is unchanged.

Product Identification (this section will describe how to identify the changed material)

Production shipment of the product incorporating the new material will begin no sooner than effective date.

Summary of Supporting Information:

The assembly plant in Penang is 100% owned and operated by Analog Devices and is equipped with the latest state-of-the-art assembly equipment. Attached you will find qualification results of LTM8002 device used to qualify the Penang assembly location. ADI product assembled in ADI Penang can be identified by the country of origin marked on the device as "MY". The product was qualified by performing extensive characterization over the full operating voltage and temperature ranges and MSL3 preconditioning. Devices from the same µModule device product family have been subjected to 1000 cycles of temperature cycles and thermal shock. ADI performs reliability testing on production lots in accordance with our Quick Reaction Reliability (QR2) Monitor Program. This monitor program is designed to provide fast feedback for possible reliability problems associated with package assembly.

Supporting Documents Attachment 1: Type: Qualification Results Summary ADI PCN 19 0162 Rev - rG311E.pdf

Attachment 2: Type: Qualification Results Summary ADI_PCN_19_0162_Rev -_rLTM8002 ADPG Rel Data.pdf

For questions on this PCN, please send an email to the regional contacts below or contact your local ADI sales representatives.						
Americas:	Europe:	Japan:	Rest of Asia:			
PCN_Americas@analog.com	PCN_Europe@analog.com	PCN_Japan@analog.com	PCN_ROA@analog.com			

Appendix A - Affected ADI Models					
Added Parts On This Revision - Product Family / Model Number (5)					
LTM8002/LTM8002HY	LTM8002/LTM8002HY#PBF	LTM8002/LTM8002HY-3.3#PBF	LTM8002 / LTM8002IY#PBF	LTM8002 / LTM8002IY-3.3#PBF	

Appendix B - Revision History					
Rev	Publish Date	Effectivity Date	Rev Description		
Rev	07-Aug-2019	09-Nov-2019	Initial Release		

Analog Devices, Inc.

Docld:6783 Parent Docld:6698 Layout Rev:7